



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC22DN20NS3 G	Issued	17. February 2022
MA#	MA005698316		
Package	PG-TDSON-8-5	Weight*	123.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.916	0.74	0.74	7409	7409
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		306	
	non noble metal	copper	7440-50-8	37.762	30.53	30.57	305341	305739
wire	non noble metal	copper	7440-50-8	0.066	0.05	0.05	537	537
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		783	
	plastics	epoxy resin	-	6.875	5.56		55591	
	inorganic material	silicondioxide	60676-86-0	41.444	33.53	39.17	335115	391489
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11738	11738
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1338	1338
solder	non noble metal	tin	7440-31-5	0.024	0.02		192	
	noble metal	silver	7440-22-4	0.030	0.02		240	
	non noble metal	lead	7439-92-1	1.135	0.92	0.96	9181	9613
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		180	
	non noble metal	copper	7440-50-8	22.292	18.02	18.05	180250	180484
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			27	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.15	9.16	91534	91653
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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